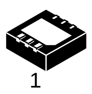
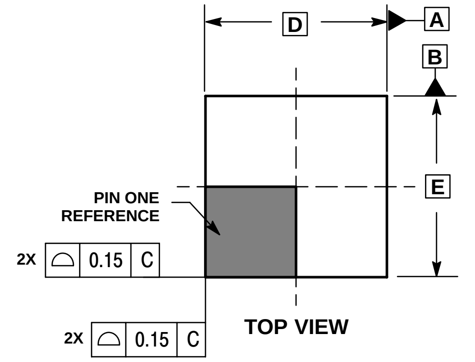


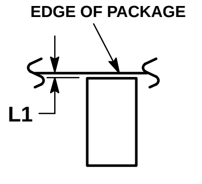
SCALE 2:1

6 PIN DFN, 3x3x0.9
CASE 488AE−01
ISSUE B

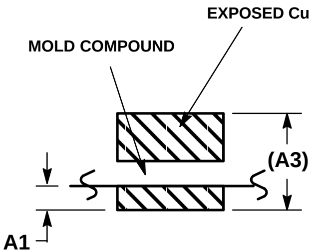
DATE 30 NOV 2005



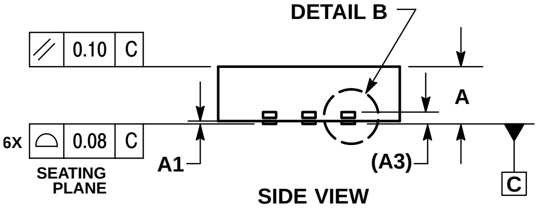
TOP VIEW



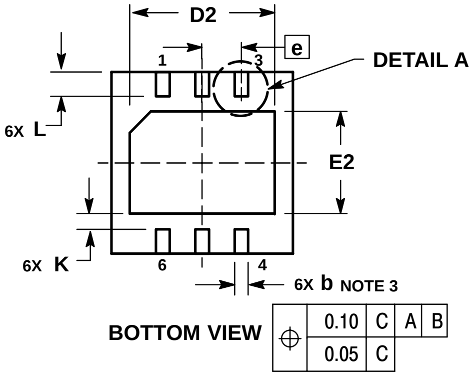
DETAIL A
BOTTOM VIEW



DETAIL B
SIDE VIEW



SIDE VIEW

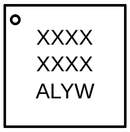


BOTTOM VIEW

NOTES:
1. DIMENSIONS AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.25 AND 0.30 MM FROM TERMINAL.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.
5. TERMINAL b MAY HAVE MOLD COMPOUND MATERIAL ALONG SIDE EDGE. MOLD FLASHING MAY NOT EXCEED 30 MICRONS ONTO BOTTOM SURFACE OF TERMINAL b.

	MILLIMETERS	
DIM	MIN	MAX
A	0.80	1.00
A1	0.00	0.05
A3	0.20	0.25
b	0.18	0.30
D	3.00 BSC	
D2	2.25	2.55
E	3.00 BSC	
E2	1.55	1.85
e	0.65 BSC	
K	0.20	---
L	0.30	0.50
L1	0.00	0.021

GENERIC MARKING DIAGRAM*



XXXX = Specific Device Code
A = Assembly Location
L = Wafer Lot
Y = Year
W = Work Week

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “ ▪”, may or may not be present.

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STATUS:	**ON SEMICONDUCTOR STANDARD**	
NEW STANDARD:		
DESCRIPTION:	**6 PIN DFN, 3X3X0.9 MM, 0.65 MM PITCH**	**PAGE 1 OF 2**

ON Semiconductor®	**DOCUMENT NUMBER:** **98AON15231D**
	PAGE 2 OF 2

ISSUE	REVISION	DATE
O	RELEASED FOR PRODUCTION. REQ. BY B. LOFTS.	13 APR 2004
A	ADDED NOTE 5, ADDED DETAIL VIEWS AND DIMENSION L1. REQ. BY B. LOFTS	26 JAN 2005
B	CHANGED DESCRIPTION FROM QFN TO DFN. REQ. BY B. LOFTS.	30 NOV 2005

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